

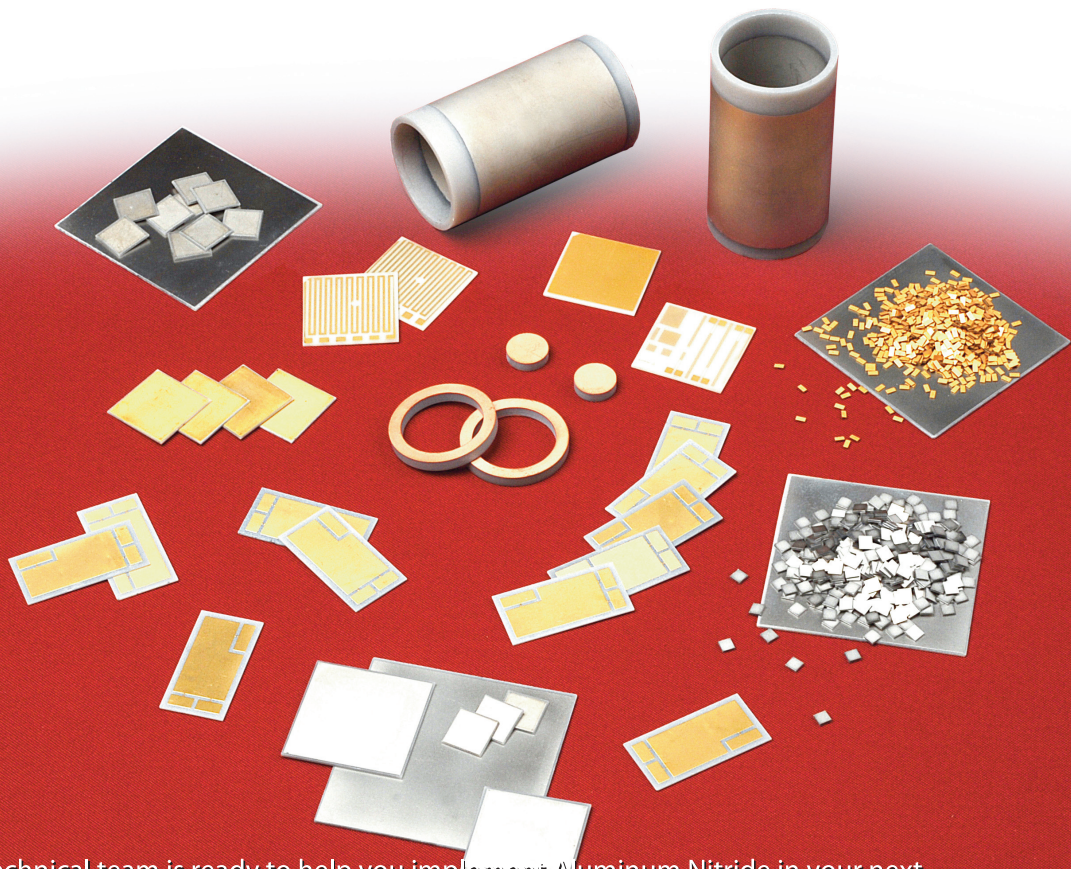
ALUMINUM NITRIDE METALLIZATION

Developing reliable metallization systems for Aluminum Nitride requires ongoing materials research. Sienna Technologies, Inc. has made substantial efforts under both in-house and government funded programs and made significant advances in developing high performance metallization technologies for Sienna's ST-100 and ST-200 Aluminum Nitride.

Sienna Technologies offers a number of thin and thick film metallizations for ST-100 AlN and ST-200 AlN.

Available Metallizations:

- Thick Film Refractory Molybdenum
- Thick Film Conductor Platinum, Gold, Copper, Silver, Gold/Palladium, and Silver/Platinum
- Thick Film Dielectric
- Thick Film Resistors
- Thin Film Metallization
- Hermetic Brazing
- Active Metal Brazing
- Glass Sealing



Sienna's technical team is ready to help you implement Aluminum Nitride in your next generation of products. Contact us for applications assistance and fast prototyping.

425-485-7272
425-485-8651 fax

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